

This exploded perspective view illustrates the assembly of a multi-layered electronic device. The components are shown in a disassembled state to reveal their internal structure and alignment. Key features include:

- 900**: The topmost layer, which appears to be a thin, rectangular frame or cover.
- 800**: A middle layer, possibly a substrate or a core, positioned below the top layer.
- 500**: A layer containing a grid of small, rectangular components, likely solder balls or micro-components, arranged in a regular pattern.
- 700**: A series of stacked layers, including:
 - 710**: A layer with a grid of small components, similar to layer 500.
 - 712a** and **712b**: Thin, rectangular layers positioned above and below the grid layer 710.
 - 714** and **716**: Additional thin layers.
 - 718** and **719**: Small, rectangular components or pads located at the edges of the grid layer 710.
- 720**: A series of stacked layers, including:
 - 722a** and **722b**: Thin, rectangular layers.
 - 723a** and **723b**: Small, rectangular components or pads.
 - 724**: A layer with a grid of small components.
 - 725a** and **725b**: Small, rectangular components or pads.
 - 726**: A layer with a grid of small components.
 - 728**: A layer with a grid of small components.
 - 730**: A layer with a grid of small components.
- 820**: The bottommost layer, which appears to be a thin, rectangular frame or cover.

FIG. 2

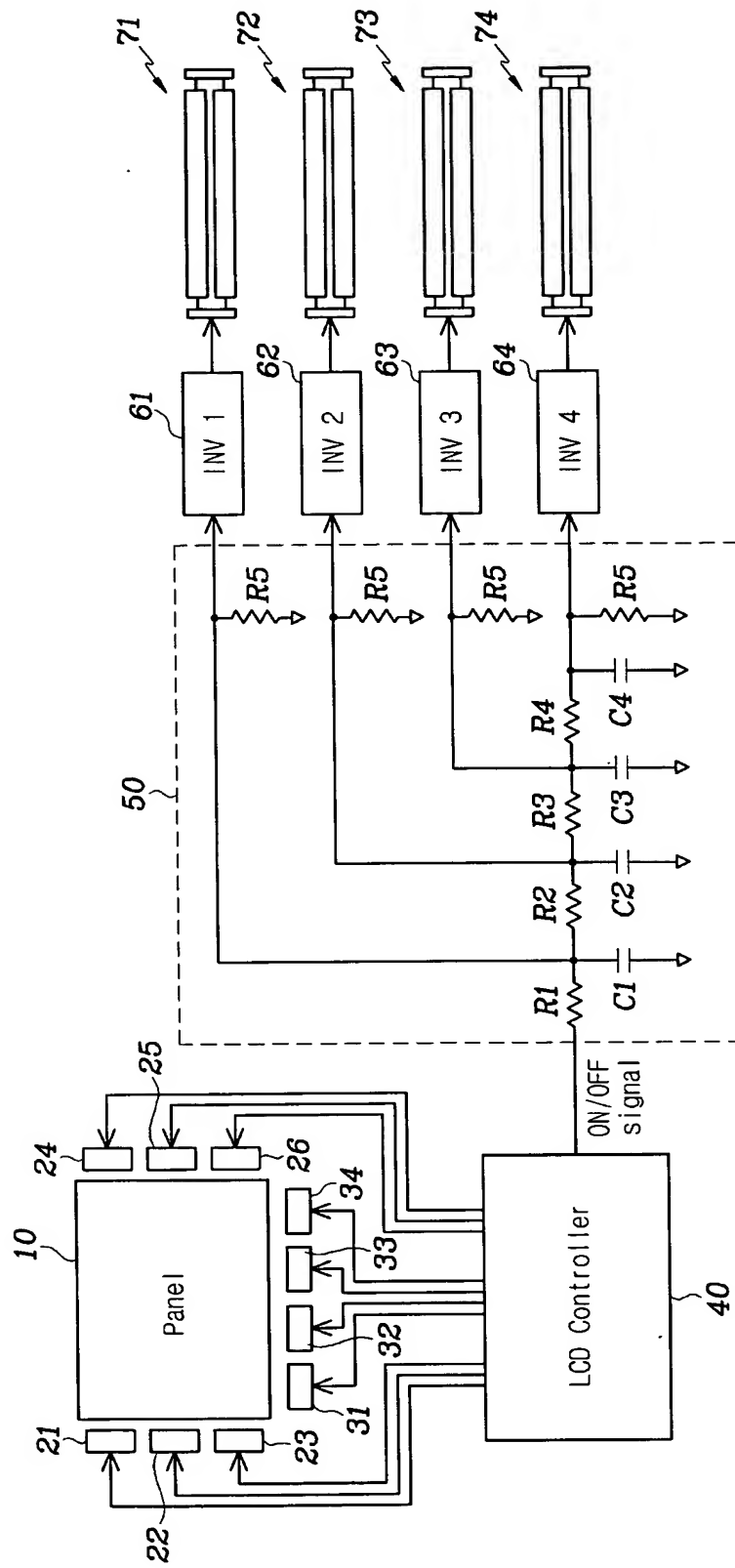


FIG.3

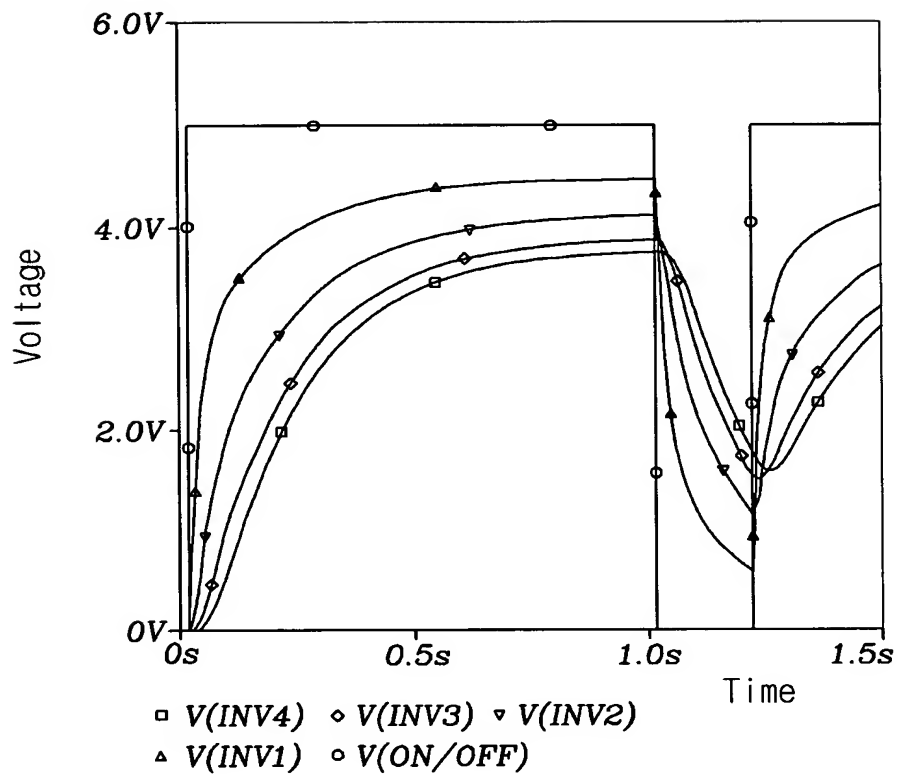


FIG. 4

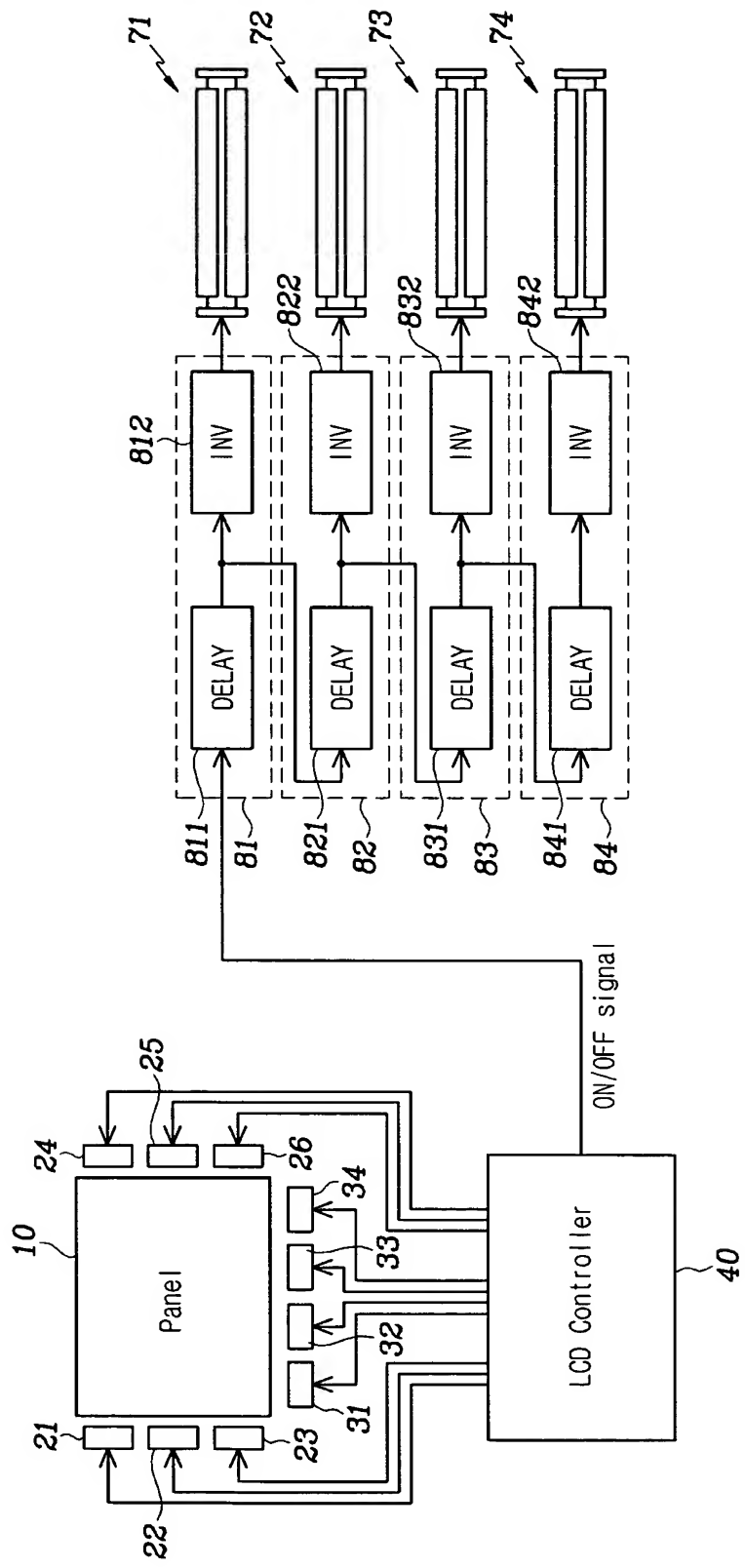


FIG.5

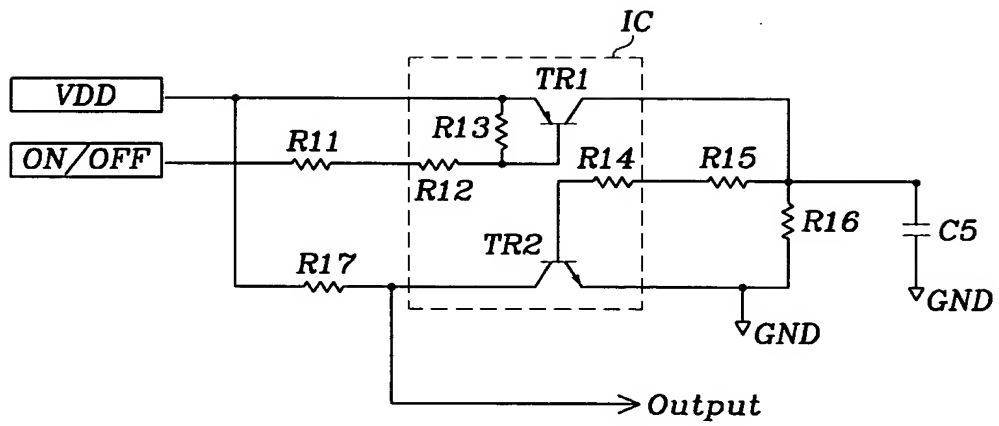


FIG.6

